

DATA SHEET

SKY77162 System Smart[®] Power Amplifier Module for CDMA / AMPS (824–849 MHz)

Applications

- Digital cellular
 CDMA
- Analog cellular
 - AMPS
- Wireless local loop (WLL)

Features

- Low voltage positive bias supply
 - 3.2 V to 4.2 V
- Low Vref
- 2.85 V, nominal
- Low IREF
 less than 1 mA
- · Good linearity
- High efficiency
- Large dynamic range
- 8-pad package
 3 x 3 x 1.2 mm
- Power down control
- Dynamic bias control
- InGaP
- IS95
- CDMA2000
- EVDO

Hazardous Substances).

The SKY77162 System Smart[®] Power Amplifier Module (PAM) is a fully matched, 8-pad, surface mount module developed for Code Division Multiple Access (CDMA), Advanced Mobile Phone Service (AMPS) and Wireless Local Loop (WLL) applications in the 824–849 MHz bandwidth. This small and efficient module packs full bandwidth coverage into a single compact package.

The SKY77162 meets the stringent IS95 CDMA linearity requirements to and exceeding 28 dBm output power, and can be driven to levels beyond 31 dBm for high efficiency in FM mode operation. A low current pad (VCONT) provides improved efficiency for the low RF power range of operation.

The single Gallium Arsenide (GaAs) Microwave Monolithic Integrated Circuit (MMIC) contains all active circuitry in the module. The MMIC contains on-board bias circuitry, as well as input and interstage matching circuits. The output match is realized off-chip and within the module package to optimize efficiency and power performance into a 50-ohm load. This device is manufactured with Skyworks' GaAs Heterojunction Bipolar Transistor (HBT) process that provides for all positive voltage DC supply operation while maintaining high efficiency and good linearity. Primary bias to the SKY77162 is supplied directly from a three-cell Ni-Cd, a single-cell Li-lon, or other suitable battery with an output in the 3.2 to 4.2 volt range. Power down is accomplished by setting the voltage on the low current reference pad to zero volts. No external supply side switch is needed as typical "off" leakage is a few microamperes with full primary voltage supplied from the battery.

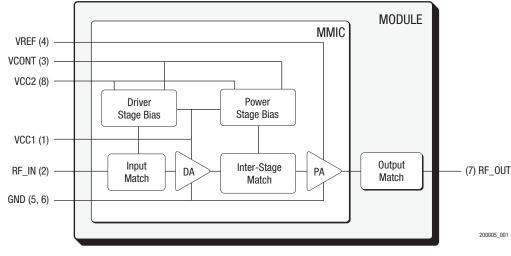


Figure 1. Functional Block Diagram

NEW Skyworks offers lead (Pb)-free "environmentally friendly" packaging that is RoHS compliant (European Parliament for the Restriction of

Electrical Specifications

The following tables list the electrical characteristics of the SKY77162 Power Amplifier. Table 1 lists the absolute maximum ratings, while Table 2 lists the recommended operating conditions

for achieving the electrical performance listed in Table . Table 3 presents a truth table for the power settings.

Paramete	r	Symbol	Minimum	Nominal	Maximum	Unit
RF Input Power	Digital	Pin_d		0.0	8.0	dBm
	Analog	Pin_a	—	3.0	8.0	ubiii
Supply Voltage		Vcc	_	3.4	6.0	Volts
Reference Voltage		VREF	—	2.85	3.0	Volts
Control Voltage		VCONT	—	TBD	3.0	Volts
Case Temperature ²	Operating	Tc	-30	25	+110	°C
	Storage	TSTG	-55	—	+125	0

Table 1. Absolute Maximum Ratings ¹

¹ No damage assuming only one parameter is set at limit at a time with all other parameters set at nominal value.

 2 Case Operating Temperature refers to the temperature of the GROUND PAD at the underside of the package.

Table 2. Recommended operating conditions						
Parameter		Symbol	Minimum	Nominal	Maximum	Unit
Output Power	U	Po_d Po_a			28 31	dBm
Operating Frequency	'	Fo	824.0	836.5	849.0	MHz
Supply Voltage	,	Vcc	3.2	3.4	4.2	Volts
Reference Voltage	,	Vref	2.75	2.85	2.95	Volts
Control voltage	Y	Vcont	1.0	—	2.0	Volts
Case Operating Tem	perature ⁻	Tc	-30	+25	+85	°C

Table 2. Recommended Operating Conditions

Table 3. Power Range Truth Table 1

V				
Power Setting	VREF	VCONT	Output Power	
High Power	2.85 V	2.0 V	28 dBm	
Low Power	2.85 V	< 1.35 V	\leq 0 dBm	
Shut Down	0.0 V	0.0 V	—	

¹ In the output power range between -10 dBm and +28 dBm, VCONT can be continuously adjusted to minimize current consumption while meeting required linearity specification.

Table 4. SKY77162 Electrical Specifications for Nominal Operating Conditions	ifications for Nominal Operating Conditions ¹
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Noise FigureNF—4.6—Input Voltage Standing Wave RatioVSWR——2:1Stability (Spurious output)S $5:1$ VSWR all phases———	CDMA / AMPS (Code Division Multiple Access / Advanced Mobile Phone Service))							
	Characterist	ics	Symbol	Condition	Minimum	Typical	Maximum	Unit
			Glow		20.0	21.5	23.0	
	Gain Conditions	Digital Mode	Gmid		23.0	25.5	27.0	dB
Analog Mode GP $p_{0, A} = 31 \text{ dBm}$ 27.5 28.5 30.5 Power Added Efficiency Digital Mode $PAE_{D, LWH}$ $VOMT = 1.35 \text{ V}$ $P_{D, D} = 0 \text{ dBm}$ 0.6 0.75 $$ Analog Mode $PAE_{D, MHH}$ $VOMT = 2.0 \text{ V}$ $P_{D, D} = 28 \text{ dBm}$ 38.5 40.5 $$ Total Supply Current $C_{C, LWH}$ $VOMT = 2.08 \text{ V}$ $P_{D, D} = 0 \text{ dBm}$ $$ 40 50 $$ Total Supply Current Ioc_{MHH} $VomT = 2.08 \text{ V}$ $P_{D, D} = 28 \text{ dBm}$ $$ 455 485 Ioc_{MHH} $VOMT = 1.35 \text{ V}$ $P_{D, D} = 28 \text{ dBm}$ $$ 40 50 Ioc_{MHH} $VOMT = 2.08 \text{ V}$ $P_{D, D} = 28 \text{ dBm}$ $$ 455 485 Ioc_{MHH} $VOMT = 2.08 \text{ V}$ $P_{D, D} = 20 \text{ Bm}$ $$ 673 700 Quiescent Current Ioc_{MHH} $VOMT = 2.0V$ 100 120 150 $-$ Adjacent Channel Power 2.3 ACP $VOMT \le 1.35 \text{ V}$ $P_{D, D} \le 20 \text{ dBm}$ $$ -56.0 -56.0			Gніgh		27.0	28.5	30.0	ub
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$		Analog Mode	Gp		27.5	28.5	30.5	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		Digital Mode	PAED_LOW		0.6	0.75	—	
Analog Mode PAEA $\rho_{0,A} = 31 \text{ dBm}$ 49.0 55.0 Total Supply Current Icc_LIGW VCONT = 1.35 V Po_D = 0 dBm 40 50 Icc_HIGH VCONT = 2.08 V Po_D = 28 dBm 455 485 Quiescent Current Icc_HIGH VCONT = 2.08 V Po_D = 31 dBm 673 700 Quiescent Current Ico_LIGW VCONT = 1.35 V Po_D = 31 dBm 673 50 1 Quiescent Current Ico_HIGH VCONT = 2.08 V Po_D = 31 dBm 673 700 1 Quiescent Current IceHIGH VCONT = 2.0V 55 71 95 1 Reference Current IEF VCONT = 2.0 V 100 120 150 1 Adjacent Channel Power ^{2.3} 885 kHz offset 1.98 MHz offset ACP1LOW VCONT < 1.35 V Po_D $\leq 28 dBm -51.0 -48.5 Harmonic Suppression SecondThird fo2fo3 Po_D \leq 28 dBm -33 -30 - Noise Power in RX Band 869-894 MHz Rk$	Power Added Efficiency		PAED_HIGH		38.5	40.5	_	%
$ \begin{array}{c c} \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$		Analog Mode	ΡΑΕΑ		49.0	55.0		
$ \begin{array}{c cc_{P}} & V_{CONT} = 2.08 V \\ \hline V_{COAT} = 3.1 \text{ dBm} & & 673 & 700 \\ \hline \\ 0 \text{ uiescent Current} & & loc_{LOW} & V_{CONT} = 1.35 V \\ \hline \\ 100 \text{ Loc}_{HGH} & V_{CONT} = 2.0 V & 55 & 71 & 95 \\ \hline \\ \text{Reference Current} & & leF & 0.2 & 1.0 & 2.0 & 0 \\ \hline \\ \text{Control Current} & & leF & 0.2 & 1.0 & 2.0 & 0 \\ \hline \\ \text{Control Current} & & leF & 0.2 & 1.0 & 120 & 150 & 0 \\ \hline \\ \text{Control Current} & & leF & 0.2 & 0.0 & 120 & 150 & 0 \\ \hline \\ \text{Control Current} & & leF & 0.2 & 0.0 & -56.0 & -50.0 \\ \hline \\ \text{Adjacent Channel Power }^{2.3} & & ACP1 \text{ luG} & P_{0,D} \leq 28 \text{ dBm} & - & -51.0 & -48.5 \\ \hline \\ \text{Adjacent Channel Power }^{2.3} & & ACP1 \text{ luG} & P_{0,D} \leq 28 \text{ dBm} & - & -51.0 & -48.5 \\ \hline \\ \text{Adjacent Channel Power }^{2.3} & & ACP2 \text{ luG} & P_{0,D} \leq 28 \text{ dBm} & - & -59.0 & -56.0 \\ \hline \\ \text{Harmonic Suppression} & & Second & fo2 & P_{0,D} \leq 28 \text{ dBm} & - & -33 & -30 & -60 \\ \hline \\ \text{Noise Power in RX Band 869-894 MHz & RxBN & P_{0,D} \leq 28 \text{ dBm} & - & -137 & -136 & d \\ \hline \\ \text{Noise Power in RX Band 869-894 MHz & RxBN & P_{0,D} \leq 28 \text{ dBm} & - & -137 & -136 & d \\ \hline \\ \text{Noise Figure} & NF & - & 4.6 & & \\ \hline \\ \text{Input Voltage Standing Wave Ratio & VSWR & - & - & - & 2:1 & 0 \\ \hline \\ \text{Stability (Spurious output)} & S & & & & \\ S & & & & & & & & & & & &$			Icc_low			40	50	
$ \begin{array}{c cc.P} & P_{0,A} = 31 \ dBm & & 6/3 & 700 \\ \hline P_{0,A} = 31 \ dBm & & 6/3 & 700 \\ \hline Quiescent Current & Ico_LOW & VCONT = 1.35 V & 25 & 35 & 50 \\ \hline P_{0,D} + 2.0 V & 555 & 71 & 95 \\ \hline Reference Current & IRFF & 0.2 & 1.0 & 2.0 & 0 \\ \hline Control Current & IcraL & VCONT = 2.0 V & 100 & 120 & 150 & 0 \\ \hline Control Current & IcraL & VCONT = 2.0 V & 100 & 120 & 150 & 0 \\ \hline P_{0,D} \leq 0 \ dBm & & -58.0 & -50.0 & -50.0 & 0 \\ \hline P_{0,D} \leq 0 \ dBm & & -51.0 & -48.5 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -51.0 & -48.5 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -59.0 & -56.0 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -59.0 & -56.0 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -33 & -30 & -50.0 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -60 & -60.0 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -60 & -48.5 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -33 & -30 & -50.0 & 0 \\ \hline P_{0,D} \geq 0 \ dBm & & -60 & -45 & 0 \\ \hline P_{0,D} \geq 28 \ dBm & & -60 & -45 & 0 \\ \hline P_{0,D} \geq 28 \ dBm & & -60 & -45 & 0 \\ \hline P_{0,D} \geq 28 \ dBm & & -137 & -136 & d \\ \hline Noise Power in RX Band 869-894 \ MHz & RxBN & P_{0,D} \geq 28 \ dBm & & -137 & -136 & d \\ \hline Noise Figure & NF & & 4.6 & & 0 \\ \hline Input Voltage Standing Wave Ratio & VSWR & & & 2:1 & 0 \\ \hline Stability (Spurious output) & S & 5:1 \ VSWR & & & -70 & 0 \\ \hline Ruggedness-No \ damage \ 4 & Ru & P_{0,D} \geq 28 \ dBm & 10:1 & & & 0 \\ \hline Turn 0n \ Time \ 5 & DC & ToNDC & & 40 & & 0 \\ \hline \end{array}$	Total Supply Current		Ісс_нідн	$Po_D = 28 \text{ dBm}$		455	485	mA
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			ICC_P		_	673	700	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Quiescent Current							mA
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Reference Current							mA
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Control Current		ICTRL	$V_{CONT} = 2.0 V$	100	120	150	μA
Adjacent Channel Power 4.0ACP2LowVCONT ≤ 1.35 V Po_D ≤ 0 dBm80.060.01.98 MHz offsetACP2HIGHPo_D ≤ 28 dBm59.056.0Harmonic SuppressionSecond Thirdfo2 fo3Po_D ≤ 31 dBm33 -6030 -45Noise Power in RX Band 869-894 MHzRxBNPo_D ≤ 28 dBm137-136dNoise FigureNF4.61Input Voltage Standing Wave RatioVSWR2:11Stability (Spurious output)S $5:1$ VSWR all phases707Ruggedness—No damage 4RuPo_D ≤ 28 dBm10:10Turn On Time 5DCToNDC4000		885 kHz offset	ACP1LOW		_	-58.0	-50.0	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Adjacent Channel Power ^{2,3}		АСР1нідн	$P_{0_D} \le 28 \text{ dBm}$	_	-51.0	-48.5	dBc
Harmonic Suppression Second Third fo2 fo3 Po_D ≤ 31 dBm -33 -60 -30 -45 Noise Power in RX Band 869-894 MHz RxBN Po_D ≤ 28 dBm -137 -136 d Noise Figure NF 4.6 1 Input Voltage Standing Wave Ratio VSWR 2:1 1 Stability (Spurious output) S 5:1 VSWR all phases -70 Turn On Time ⁵ DC ToNDC 40		1.98 MHz offset	ACP2LOW		—	-80.0	-60.0	übe
Harmonic Suppression Third fo3 $P_{0D} \le 31 \text{ dBM}$ 60 45 Noise Power in RX Band 869-894 MHz RxBN $P_{0D} \le 28 \text{ dBm}$ -137 -136 d Noise Figure NF 4.6 1 Input Voltage Standing Wave Ratio VSWR 2:1 1 Stability (Spurious output) S $5:1 \text{ VSWR}$ all phases -70 -70 1 Turn On Time 5 DC ToNDC 40 -			АСР2нідн	$Po_D \leq 28 \ dBm$	—	-59.0	-56.0	
Noise Power in RX Band 869-894 MHz RxBN $P_{0_{-}D} \le 28 \text{ dBm}$ 137 136 d Noise Figure NF 4.6 1 Input Voltage Standing Wave Ratio VSWR 2:1 1 Stability (Spurious output) S $5:1 \text{ VSWR}$ all phases -70 Ruggedness—No damage ⁴ Ru $P_{0_{-}D} \le 28 \text{ dBm}$ 10:1 0 Turn On Time ⁵ DC ToNDC 40 1	Harmonic Suppression			$Po_{\tt D} \le 31 \ dBm$				dBc
Input Voltage Standing Wave RatioVSWR——2:1Stability (Spurious output)S $5:1$ VSWR all phases————Ruggedness—No damage 4Ru $Po_D \le 28$ dBm10:1———VTurn On Time 5DCToNDC——40——	Noise Power in RX Band 869-89	94 MHz	RxBN	$Po_D \le 28 \text{ dBm}$	_			dBm/Hz
Stability (Spurious output)S $5:1 VSWR$ all phases————Ruggedness—No damage 4Ru $Po_D \le 28 \text{ dBm}$ 10:1——— V Turn On Time 5DCToNDC—40— V	Noise Figure		NF		—	4.6	_	dB
Stability (Spurious output)Sall phases/0Ruggedness—No damage 4Ru $Po_D \le 28 \text{ dBm}$ 10:1Turn On Time 5DCToNDC40	Input Voltage Standing Wave Ra	atio	VSWR		_	_	2:1	
Turn On Time ⁵ DC ToNDC — 40 —	Stability (Spurious output)		S		_	_	-70	dBc
lurn Un Lime ^o	Ruggedness—No damage ⁴		Ru	$Po_D \le 28 \text{ dBm}$	10:1	—		VSWR
	Turn On Time ⁵							μs
Turn Off Time ⁵ DC ToFFDC — 40 — 1 RF ToFFRF — 5 — 5 — 5 — 5 — 5 — 5 — 5 — 5 — 5 — 5 3 3 5 3 3 5 3 3 5 3 3 5 3 3 5 3 3 5 3 3 5 3 3 5 3	Turn Off Time ⁵	DC	TOFFDC		_	40		μs

¹ Per Table 2 over dynamic range up to 28 dBm output power Unless otherwise specified.

² ACP is specified per IS95 as the ratio of the total in-band power (1.23 MHz BW) to adjacent power in a 30 kHz BW.

³ For CDMA2000 test configured as [PCH @ -3.75 dB, DCCH-9600 bps @ 0 dB; SCH0-9600 bps @ 0 dB] and other test configurations that yield a peak-to-average up to 4.5 dB for CCDF = 1%, up to 1. dB power back off from the maximum listed for IS95 may be required to meet specified maximum ACP performance under worst-case conditions.

⁴ All phases, time = 10 seconds.

 5 TovDC is time required to reach stable quiescent bias (±10%) after VREF is switched high.

TofFDC is time required for battery to decrease to $< 100 \ \mu$ A after VREF is switched low.

After Ica is stable, The ToNRF is time to reach final output power (±1 dB) once RF input is applied. ToFFRF is time required for Po to drop 30 dB once RF input is removed.

Characterization Data

The following graphs illustrate the characteristics of a typical SKY77162 power amplifier designed for operation in the cellular frequency band (824–849 MHz). This amplifier was selected by characterizing a group of devices and then selecting a part with average electrical performance for both nominal and the full range of recommended operating conditions, including worst case limits. Figure 2 through 8 illustrate the digital signal

characteristics of the SKY77162. Shown are power sweep characteristics for key performance parameters, over temperature and frequency, up to 28.5 dBm output power. The data was taken up to and including 16 dBm output power with the bias mode control pad setting of VCONT = 1.8 volts. Beyond 16 dBm output power, VCONT was set to 2.0 V.

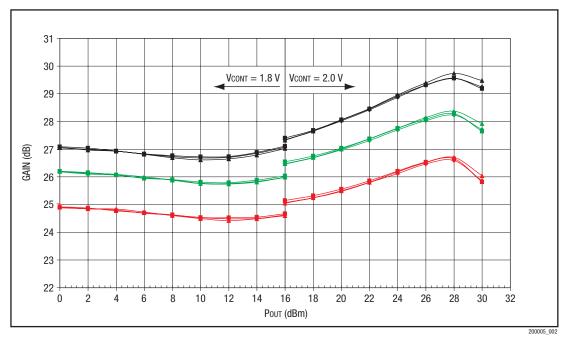


Figure 2. Gain vs. Output Power

Legend		
── ─ ── 824.0 MHz @ −30 °C		
→ 836.5 MHz @ -30 °C	→→ 836.5 MHz @ +25 °C	→→ 836.5 MHz @ +85 °C
—▲— 849.0 MHz @ –30 °C	— ▲ — 849.0 MHz @ +25 ℃	— ▲ — 849.0 MHz @ +85 °C

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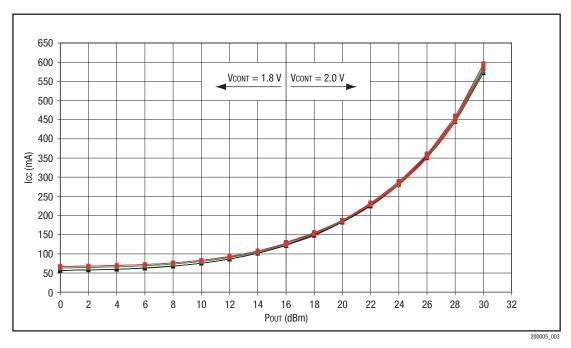
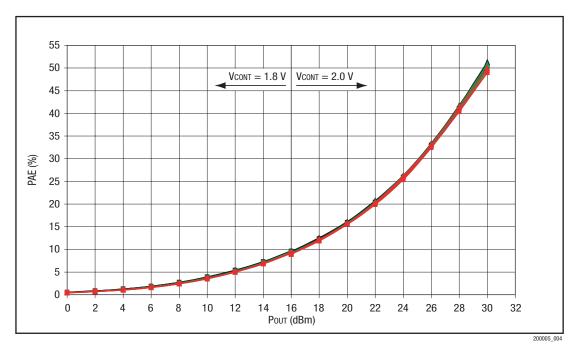
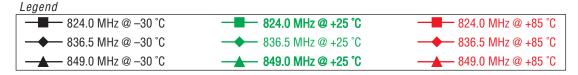


Figure 3. Supply Current vs. Output Power







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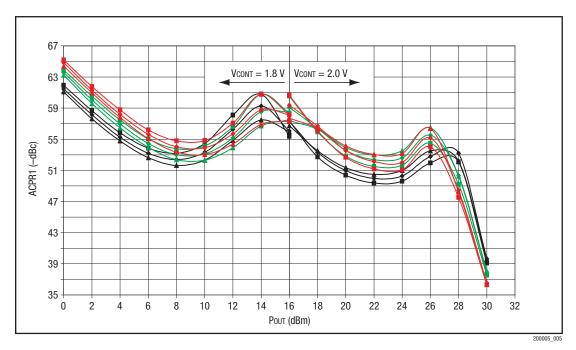


Figure 5. Adjacent Channel Power Ratio 1 vs. Output Power

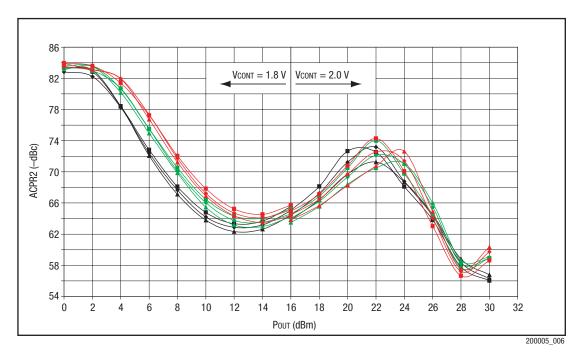
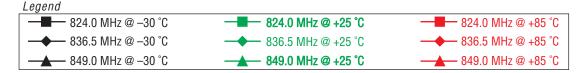


Figure 6. Adjacent Channel Power Ratio 2 vs. Output Power



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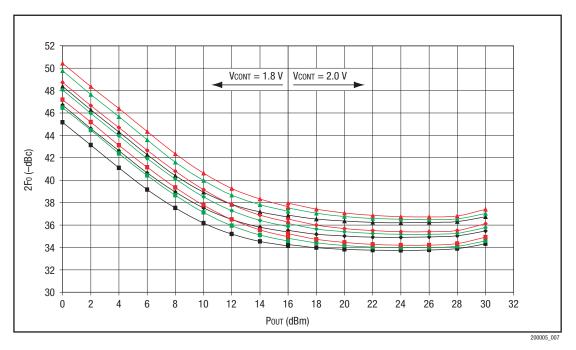
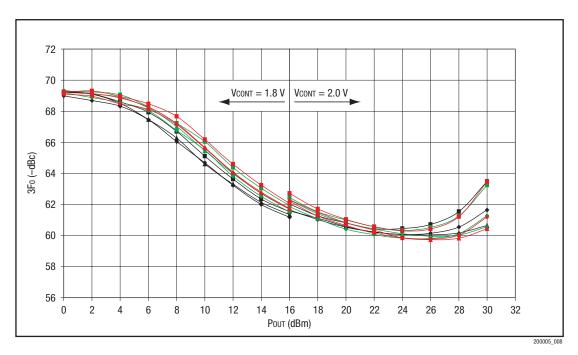
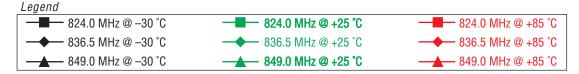


Figure 7. Second Harmonic vs. Output Power





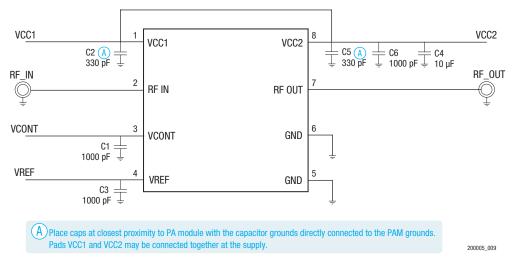


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Evaluation Board Description

The evaluation board is a platform for testing and interfacing design circuitry. To accommodate the interface testing of the SKY77162, the evaluation board schematic and evaluation board

assembly diagram are included for preliminary analysis and design. Figure 9 shows the basic schematic of the board for the 824 MHz to 849 MHz range.





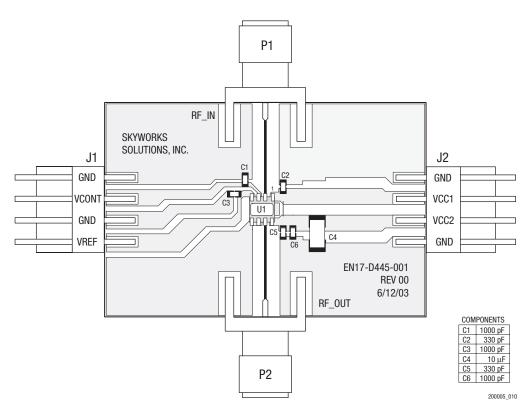
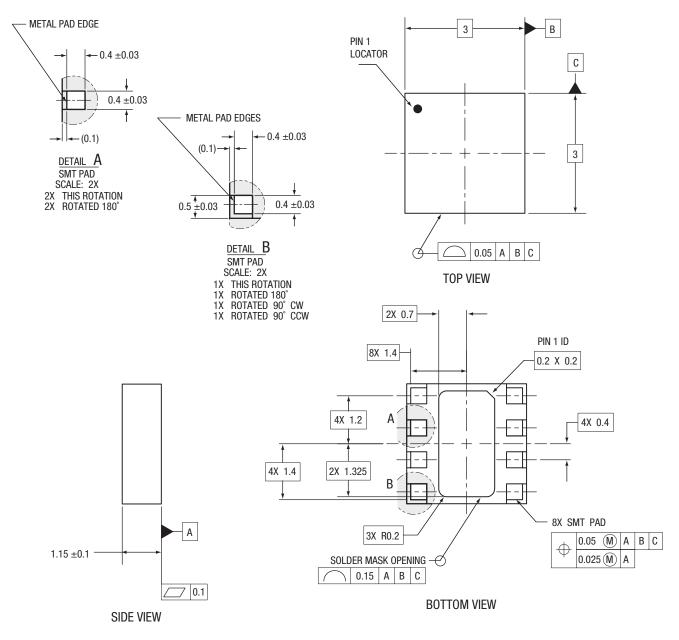


Figure 10. Evaluation Board Assembly Diagram

Package Dimensions and Pad Descriptions

The SKY77162 is a multi-layer laminate base, overmold encapsulated modular package designed for surface mount solder attachment to a printed circuit board. Figure 11 is a mechanical drawing of the pad layout for this package. Figure 12 provides a recommended phone board layout footprint for the PAM to help the designer attain optimum thermal conductivity, good grounding, and minimum RF discontinuity for the 50 ohm terminals. Figure 13 shows the pad names and the pad numbering convention, which starts with pad 1 in the upper left and increments counter-clockwise around the package. Figure 14 illustrates typical case markings.



NOTES: Unless otherwise specified

1. DIMENSIONING AND TOLERANCES IN ACCORDANCE WITH ASME Y14.5M-1994.

2. SEE APPLICABLE BONDING DIAGRAM AND DEVICE ASSEMBLY DRAWING FOR DIE AND COMPONENT PLACEMENT.

3. PADS ARE SOLDER MASK DEFINED ON ALL INSIDE EDGES.

4. ALL DIMENSIONS ARE IN MILLIMETERS.

200005_011

Figure 11. SKY77162 Package Dimensional Drawing (All Views)

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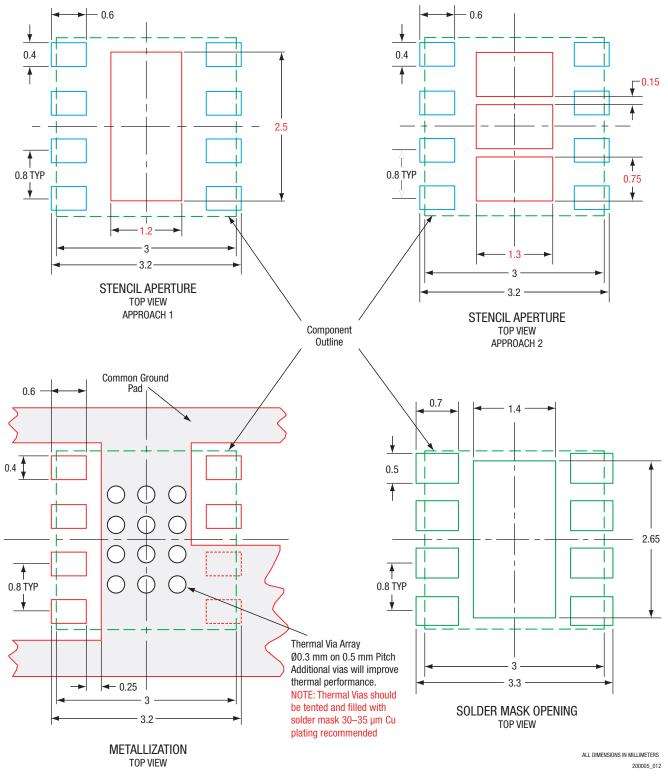


Figure 12. Phone PCB Layout Footprint for 3 x 3 mm, 8-Pad Package - SKY77162

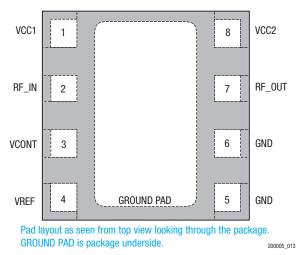


Figure 13. SKY77162 Pad Configuration and Pad Names (Top View)

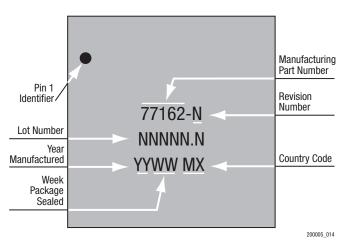


Figure 14. Typical Case Markings

Package and Handling Information

Because of its sensitivity to moisture absorption, this device package is baked and vacuum-packed prior to shipment. Instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken, otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY77162 is capable of withstanding an MSL3/250 °C solder reflow. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is attached in a reflow oven, the temperature ramp rate should not exceed 3 °C per second; maximum temperature should not exceed 250 °C. If the part is manually attached, precaution should be taken to insure that the part is not subjected to temperatures exceeding 250 °C for more than 10 seconds. For details on both attachment techniques, precautions, and handling

procedures recommended by Skyworks, please refer to Skyworks Application Note: *PCB Design and SMT Assembly/Rework,* Document Number 101752. Additional information on standard SMT reflow profiles can also be found in the *JEDEC Standard J-STD–020*.

Production quantities of this product are shipped in the standard tape-and-reel format. For packaging details, refer to Skyworks Application Note: *Tape and Reel – RF Modules,* Document Number 101568.

Electrostatic Discharge Sensitivity

The SKY77162 is a Class 2 device. Figure 15 lists the Electrostatic Discharge (ESD) immunity level for each non-ground pad of the SKY77162 product. The numbers in Figure 15 specify the ESD threshold level for each pad where the I-V curve between the pad and ground starts to show degradation.

The ESD testing was performed in compliance with MIL-STD-883E Method 3015.7 using the Human Body Model. If ESD damage threshold magnitude is found to consistently exceed 2000 volts on a given pad, this so is indicated. If ESD damage threshold below 2000 volts is measured for either polarity, numbers are indicated that represent worst case values observed in product characterization.

Various failure criteria can be utilized when performing ESD testing. Many vendors employ relaxed ESD failure standards, which fail devices only after "the pad fails the electrical specification limits" or "the pad becomes completely non-functional". Skyworks employs most stringent criteria and fails devices as soon as the pad begins to show any degradation on a curve tracer.

To avoid ESD damage, both latent and visible, it is very important that the product assembly and test areas follow the Class-1 ESD handling precautions listed in Table 4.

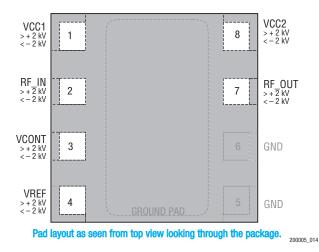


Figure 15. ESD Sensitivity Areas (Top View)

Table 4. Precautions for Hand	ling GaAs IC-based Products to Avoid Induced Damage
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	Wrist Straps	
Personnel Grounding	Conductive Smocks, Gloves and Finger Cots	
	Antistatic ID Badges	
Facility	Relative Humidity Control and Air Ionizers	
raciiity	Dissipative Floors (less than $10^9 \Omega$ to GND)	
	Dissipative Table Tops	
	Protective Test Equipment (Properly Grounded)	
Protective Workstation	Grounded Tip Soldering Irons	
	Conductive Solder Suckers	
	Static Sensors	
	Bags and Pouches (Faraday Shield)	
	Protective Tote Boxes (Conductive Static Shielding)	
Protective Packaging & Transportation	Protective Trays	
	Grounded Carts	
	Protective Work Order Holders	

Ordering Information

Model Number	Manufacturing Part Number	Product Revision	Package	Operating Temperature
SKY77162	SKY77162			−30 °C to +85 °C

Revision History

Revision	Level	Date	Description
А		May 2, 2006	Initial Release

References

Application Note: PCB Design and SMT Assembly/Rework, Document Number 101752. Application Note: Tape and Reel Information – RF Modules, Document Number 101568 JEDEC Standard J–STD–020

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